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National R&D Centre in ICT



# TECH TALK

## On Failure Analysis, Engineering Materials and Reliability Testing

6 February 2018 | 8.00 am to 4.00 pm  
MIMOS Berhad, Technology Park Malaysia, Kuala Lumpur, Malaysia

Please use registration form to register | Registration by 1 February 2018



### Bridging Industrial Issues & Applications with Engineering Knowledge

by Prof. Ir. Dr. Cheong Kuan Yew

School of Materials and Mineral Resources Engineering, Universiti Sains Malaysia

In this session, importance of engineering knowledge on solving typical engineering issues particularly in High Volume Manufacturing (HVM) environment will be elaborated. The role of engineering materials in typical failures related to HVM process on the performance of engineering products will be explained. Know-how of failure analysis and fundamental concepts needed to resolve engineering issues will also be shared.



### Failure Analysis of Semiconductor Devices

by Dr. Muhammad Nubli Zulkifli

Electrical Engineering Section, Universiti Kuala Lumpur, Malaysia

Nowadays semiconductor devices are becoming more complex and compact. This has introduced a lot of issues especially the device failures and how to identify the root cause of the failure. Failure Analysis (FA) is a tool that can be utilised to give valuable insight into the causes of failure and provide inputs for product improvement. FA also can be used to evaluate the reliability of the electronic system. The objectives of this presentation are to introduce the methods in FA, failure mechanisms and how to identify the root cause of failures.



### Reliability Prediction Methods

by Assoc. Prof. Ir. Dr. Mohd. Khairil Rahmat

Electrical Engineering Section, Universiti Kuala Lumpur, Malaysia

The session will highlight the reliability parameters prediction methods for the UPS systems namely the Reliability Block Diagram (RBD) technique, Boolean Truth Table, Probability Tree, Fault Tree Analysis, Monte-Carlo Simulation method and Field Data estimation methods, providing a useful and fast method to evaluate the system's failure rates, Mean Time Between Failures (MTBF), Availability and Unavailability of the UPS systems.

### Program Schedule

- 8.00am :**  
Registration
- 9.15am :**  
Welcoming Remark
- 9.30am :**  
Bridging Industrial Issues & Applications with Engineering Knowledge
- 11.00am :**  
Refreshment
- 11.15am :**  
Failure Analysis of Semiconductor Devices
- 1.00pm :**  
Lunch break
- 2.30pm :**  
Reliability Prediction Methods
- 4.00 pm :**  
Networking and Refreshment

To Register & for More Information:

Business Development (MSSB), MIMOS Semiconductor (M) Sdn Bhd  
Call : +603-8995 5000 ext. 55279 (Fara) or 55625 (Amy)  
Email : faradaya.machmud@mimos.my or letchumy@mimos.my



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